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Renesas Electronics Corporation

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SH7080 Group

I²C2 Single-Master Reception (Reading from I²C-Bus EEPROM)

Introduction

This application note describes the receiving operation by the I²C bus interface 2 module (I²C2) in single-master mode. Please use this application note as a guide in designing user programs.

Although the programs given in this application note have been verified for correct operation, we strongly recommend that the user confirm correct operation before applying the programs in the actual application.

Target Device

SH7085

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1. Specifications

- The SH7085's I²C bus interface 2 module (I²C2) is used to read 10 bytes of data from a two-wire serial EEPROM (HN58X2416; 16k bits; 2k words × 8 bits).
- The connection is made in single-master configuration, in which the SH7085 is the master device.
- The device code of the connected EEPROM is B'1010.
- Before reading data from the EEPROM, the EEPROM bus state is initialized.*
- Data is read from addresses H'0000 to H'0009 in the EEPROM.
- After 1 byte of data has been received, the acknowledge bit (ACK = 0) is output. (However, ACK = 1 is output after reception of the last byte.)
- The frequency of the I²C bus data transfer clock is 400 kHz.

Figure 1 shows an example of connection between the SH7085 and EEPROM, and table 1 shows the SH7085's I²C2 settings. Table 2 shows the device address word of the EEPROM used in the sample task.

Note: The EEPROM's SDA bus is forcibly placed in the input state, anticipating the case when the EEPROM is unable to receive from the master device because of the EEPROM's SDA bus remaining in the output state as a result of, for example, communication having been halted while the master device is receiving data from the EEPROM.

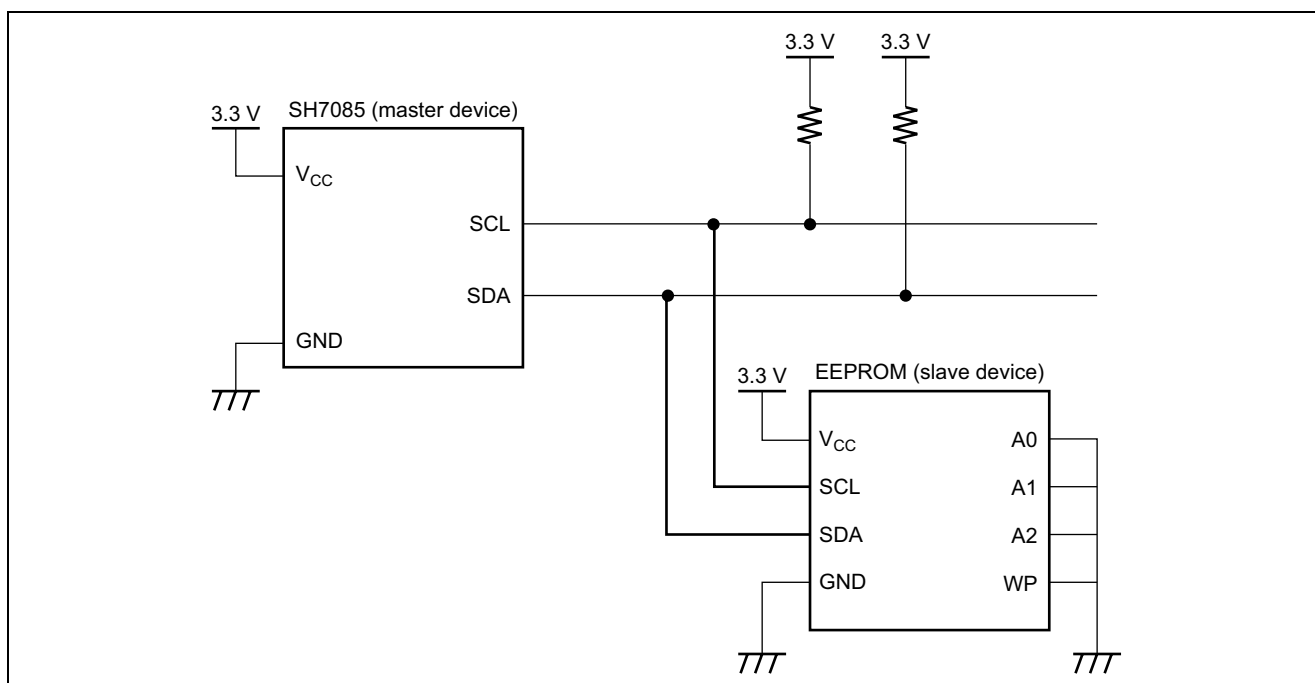


Figure 1 Example of Connection between SH7085 and EEPROM

Table 1 I²C2 Settings of SH7085

Item	Setting
Operating mode	Master reception mode
Transfer clock	400 kHz (P _φ = 40 MHz)
Data bit length	9 bits (including the ACK bit)
Wait cycles inserted between data and ACK	None
Interrupt	None
ACK output	Outputs 1 only when the last data is received. Outputs 0 while data is received continuously.

Table 2 Device Address Word of EEPROM

Device Code				Device Address Code			R/W Code
1	0	1	0	a10	a9	a8	R = 1, W = 0

Note: a10 to a8 are the upper 3 bits of the EEPROM address.

2. Conditions for Application

Operating frequency: Internal clock: 80 MHz
 Bus clock: 40 MHz
 Peripheral clock: 40 MHz
 MTU2 clock: 40 MHz
 MTU2S clock: 80 MHz

C compiler: Version 7.1.04 from Renesas Technology Corp.

3. Summary of MCU Functions Used

In this sample task, the I²C bus (Inter IC bus) is used to read data from the EEPROM.

3.1 I²C Bus Interface 2 (I²C2)

The I²C bus interface 2 (I²C2) conforms to the I²C bus interface specifications set up by Philips, and provides a subset of the I²C functions. Figure 2 shows a block diagram of the I²C2 module.

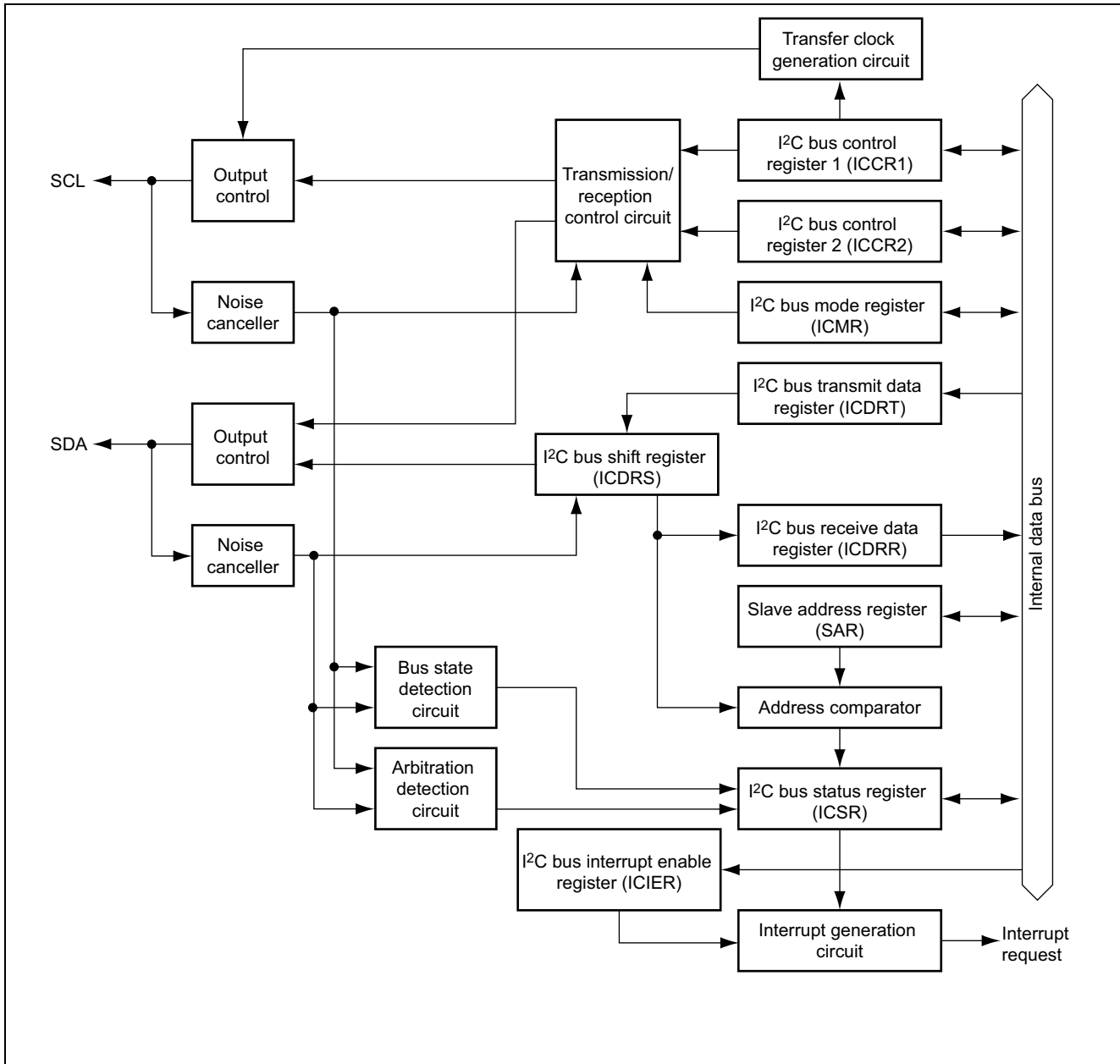


Figure 2 Block Diagram of I²C2 Module

- The I²C bus control register 1 (ICCR1) sets I²C2 operations.
- The I²C bus control register 2 (ICCR2) generates start and stop conditions, drives the SDA pin, monitors the SCL pin, and controls resetting of the I2C bus control circuitry.
- The I²C bus mode register (ICMR) selects MSB- or LSB-first transfer, controls the wait states in master mode, and selects the number of bits to be transferred.
- The I²C bus interrupt enable register (ICIER) enables interrupts, selects the use of the acknowledge bit, sets the acknowledge bit for transmission, and checks the received acknowledge bit.
- The I²C bus status register (ICSR) consists of various interrupt request and status flags.
- The I²C slave address register (SAR) selects a format and sets the slave address.
- The I²C bus transmit data register (ICDRT) holds data for transmission.
- The I²C bus receive data register (ICDRR) holds the received data.
- The I²C bus shift register (ICDRS) is used to transmit/receive data; this register cannot be accessed by the CPU.

4. Operation

In this sample task, the EEPROM bus state is initialized before data is read from the EEPROM.

4.1 EEPROM Bus Initialization

The EEPROM bus initialization here means to forcibly place the EEPROM's SDA bus into the input state. This initialization should be applied when the EEPROM is unable to receive from the master device because of the EEPROM's SDA bus remaining in the output state as a result of, for example, communication having been halted while the master device is receiving data from the EEPROM.

In the initialization processing, the SCL and SDA bus lines are driven by using the port I/O (general-purpose I/O) function. After generating a start condition, the MCU outputs dummy data (H'FF), receives acknowledge (ACK) from the EEPROM, and then generates a stop condition.

Figure 3 shows the initialization processing, and the software and hardware processing in the figure are described in table 3.

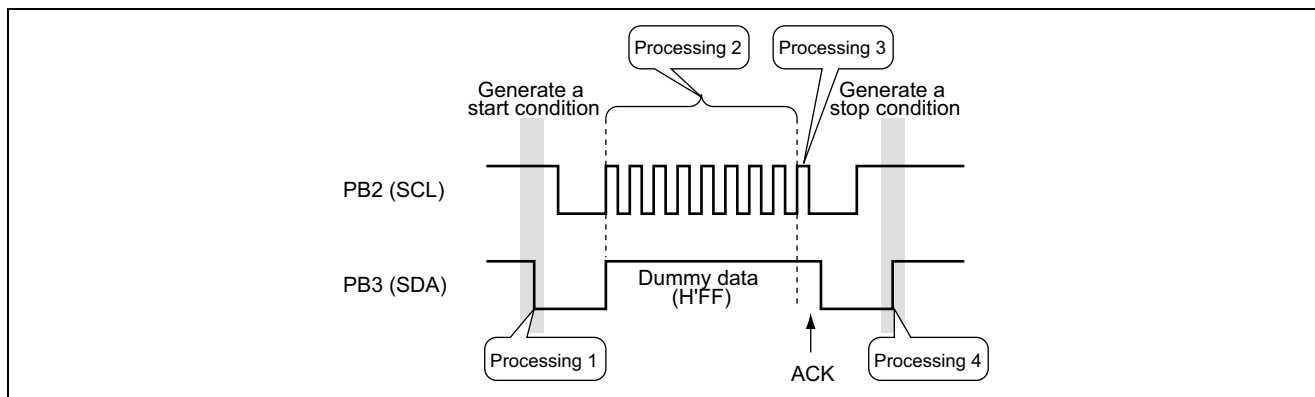


Figure 3 EEPROM Bus Initialization Processing

Table 3 Software and Hardware Processing in Bus Initialization

	Software Processing	Hardware Processing
Processing 1	<ul style="list-style-type: none"> Set PB2 (SCL) and PB3 (SDA) as port (general input/output) pins. Set the output level on PB2 and PB3 to high. Set the output level on PB3 to low to generate a start condition. Set the output level on PB2 to low. 	—
Processing 2	<ul style="list-style-type: none"> Output the transfer clock by changing the output level on PB2 with use of a software wait timer. Fix the output level on PB3 to high to transmit dummy data (H'FF). 	—
Processing 3	<ul style="list-style-type: none"> Output the transfer clock (for receiving the acknowledge bit) from PB2. Set PB3 as an input pin. Read the state on the PB3 pin. 	—
Processing 4	<ul style="list-style-type: none"> Set the output level on PB2 and PB3 to low. Set the output level on PB3 to high to generate a stop condition. 	—

4.2 Reading Data from EEPROM

In this sample task, the address (H'0000) is specified by Random Reading, and then 10 bytes of data are continuously read by Sequential Read.

Figure 4 shows the contents of communication when data are read from the EEPROM.

After a start condition is generated, the device address word is transmitted with the R/W code set to 0 (specifying write operation). The lower byte of the EEPROM read start address is then transmitted.

A start condition is generated again to start reading. After the second generation of a start condition, the device address word is transmitted with the R/W code set to 1 (specifying read operation). This makes data to be output from the EEPROM sequentially in accordance with the I²C format.

The master outputs the acknowledge bit (ACK) on receiving one byte of data. The EEPROM outputs the next byte on receiving ACK = 0. The master outputs ACK = 1 on receiving the last byte and generates a stop condition.

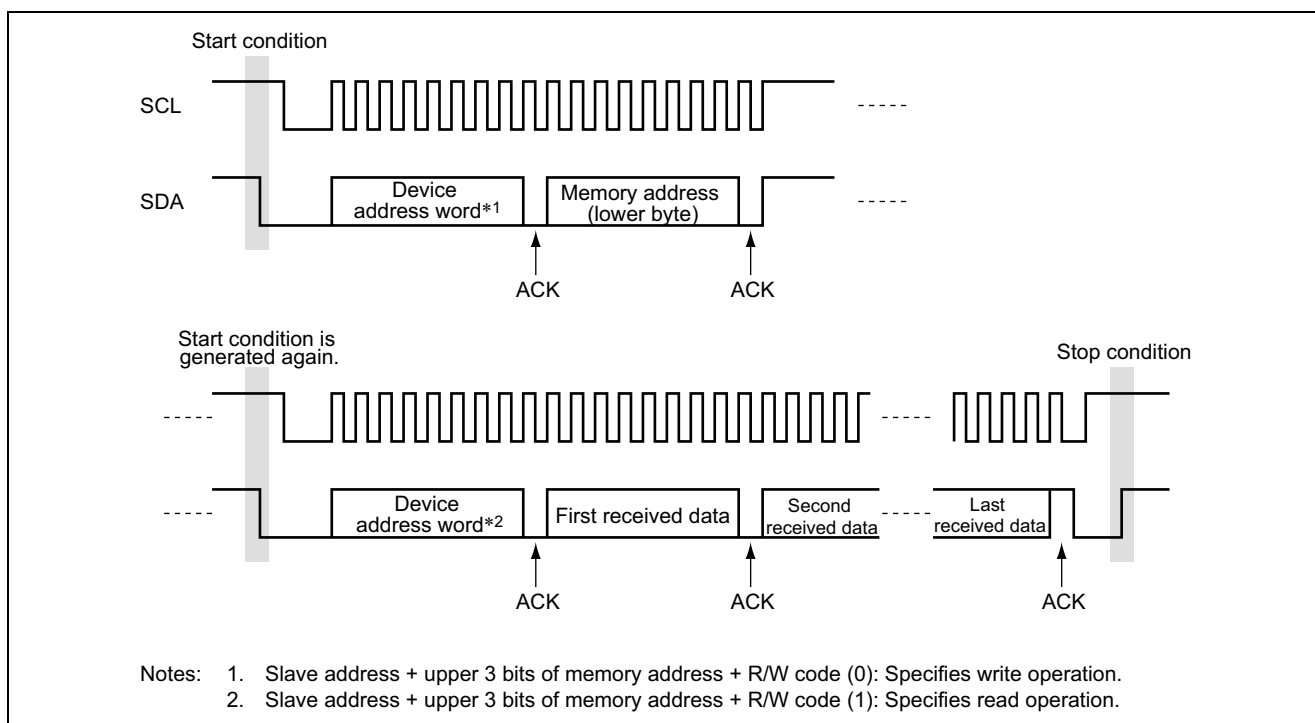


Figure 4 Contents of Communication When Data are Read from EEPROM

Figure 5 shows the operation when data reading from the EEPROM is started (start condition generated again), and figure 6 shows the ending operation. The software and hardware processing in figures 5 and 6 are described in tables 4 and 5, respectively.

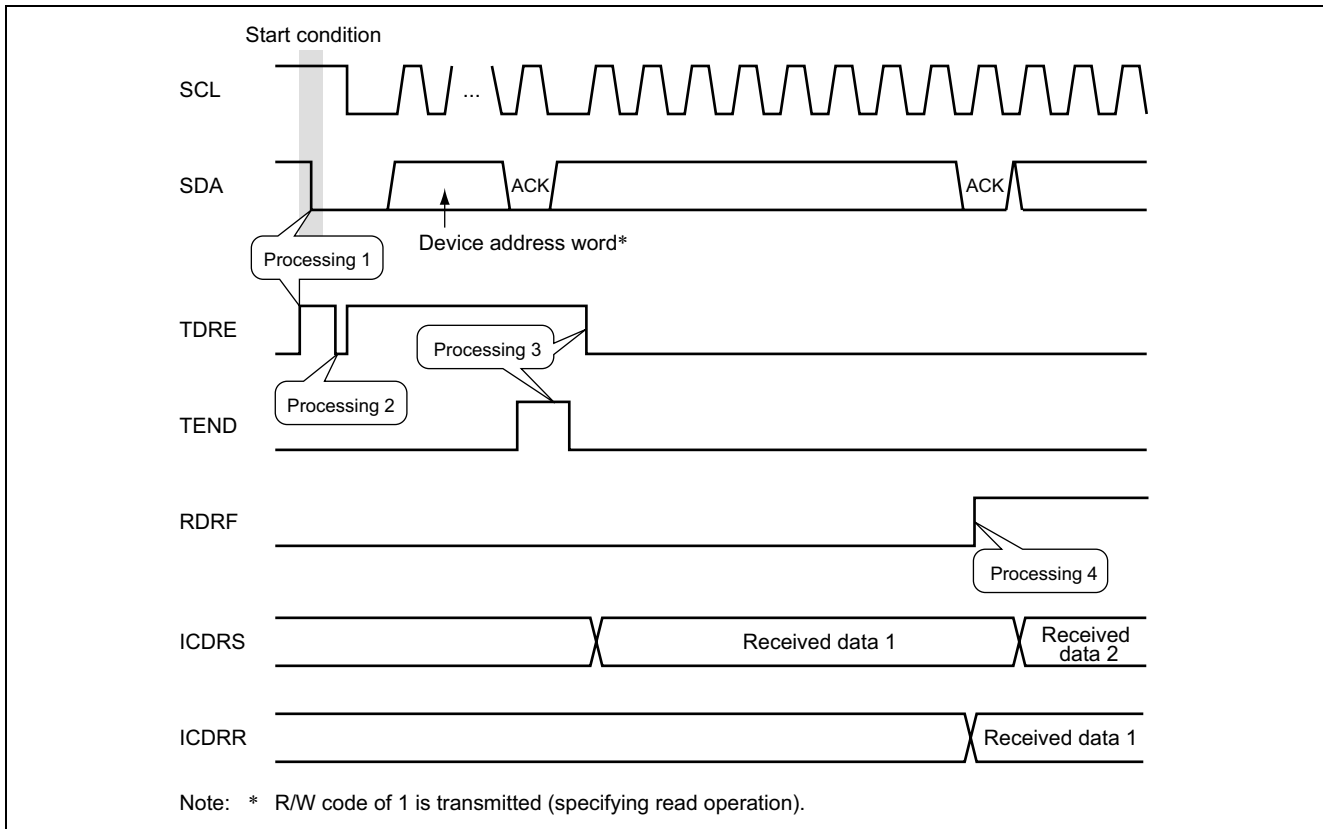


Figure 5 Operation when Reading from EEPROM Starts

Table 4 Software and Hardware Processing when Reading from EEPROM Starts

	Software Processing	Hardware Processing
Processing 1	Set BBSY to 1 and SCP to 0 in the ICCR2 register.	<ul style="list-style-type: none"> • Generate a start condition (second time). • Set the TDRE bit in the ICSR register to 1.
Processing 2	Write the device address word data to the ICDRT register (specifying read operation).	<ul style="list-style-type: none"> • Clear the TDRE bit in the ICSR register to 0. • Transfer the transmit data in the ICDRT register to the ICDRS register, and then output the data from the SDA pin. • Set the TDRE bit in the ICSR register to 1.
Processing 3	<ul style="list-style-type: none"> • Confirm that TEND in the ICSR register is 1. • Check the received acknowledge through the ACKBR bit in the ICIER register. • Clear the TEND bit in the ICSR register to 0. • Clear the TRS bit in the ICCR1 register to 0 (master reception mode). • Clear the TDRE bit in the ICSR register to 0. • Dummy-read the ICDRR register (starting reception). 	<ul style="list-style-type: none"> • Set the TEND bit in the ICSR register to 1 after outputting the last bit of the transmit data. • Output the clock for reception by dummy-reading the ICDRR register.
Processing 4	<ul style="list-style-type: none"> • Confirm that RDRF in the ICSR register is 1. • Read the ICDRR register. 	<ul style="list-style-type: none"> • Output the acknowledge bit after receiving the last bit. • Transfer the received data in the ICDRS register to the ICDRR register. • Set the RDRF bit in the ICSR register to 1. • Clear the RDRF bit in the ICSR register to 0 after the ICDRR register is read.

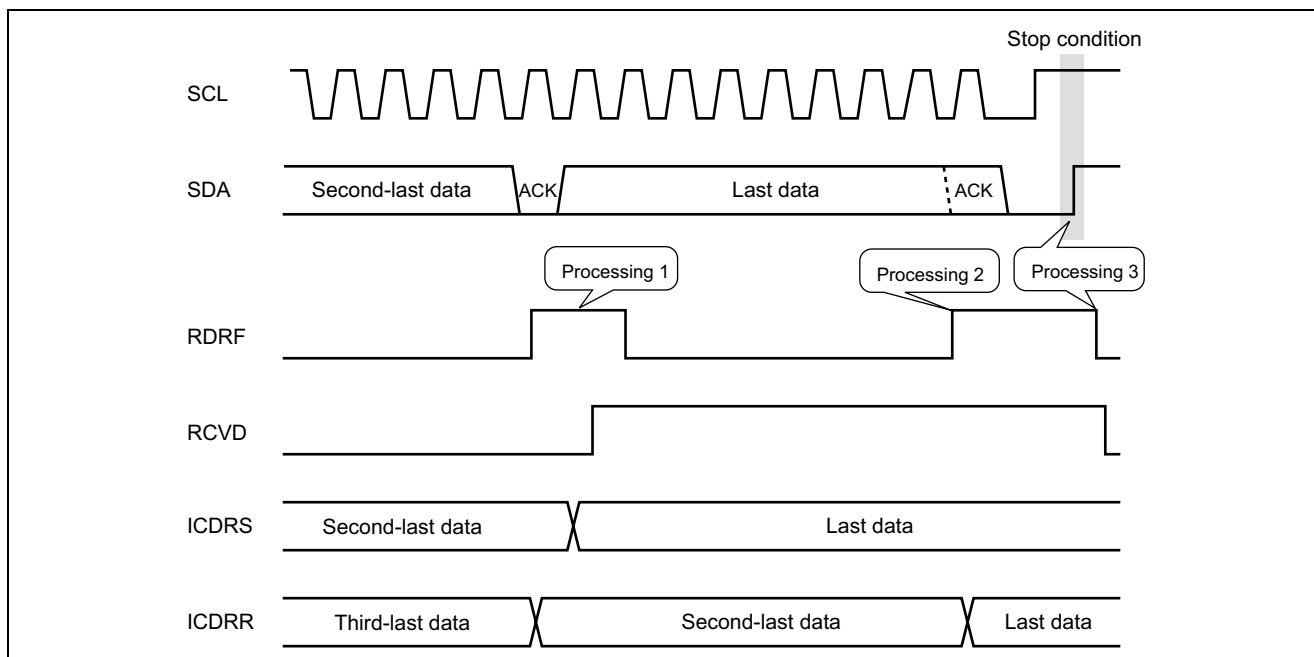


Figure 6 Operation when Reading from EEPROM Ends

Table 5 Software and Hardware Processing when Reading from EEPROM Ends

	Software Processing	Hardware Processing
Processing 1	<ul style="list-style-type: none"> • Confirm that RDRF in the ICSR register is 1. • Set the ACKBT bit in the ICIER register to 1. • Set the RCVD bit in the ICCR1 register to 1. • Read the ICDRR register. 	<ul style="list-style-type: none"> • Transfer the received data in the ICDRS register to the ICDRR register. • Set the RDRF bit in the ICSR register to 1. • Clear the RDRF bit in the ICSR register to 0 after the ICDRR register is read.
Processing 2	<ul style="list-style-type: none"> • Confirm that RDRF in the ICSR register is 1. • Clear the STOP bit in the ICSR register to 0. 	<ul style="list-style-type: none"> • Transfer the received data in the ICDRS register to the ICDRR register. • Set the RDRF bit in the ICSR register to 1.
Processing 3	<ul style="list-style-type: none"> • Set BBSY and SCP in the ICCR2 register to 0. • Confirm that STOP in the ICSR register is 1. • Read the ICDRR register (last data). • Clear the RCVD bit in the ICCR1 register to 0. • Set MST and TRS in the ICCR1 register to 0 (slave reception mode). 	<ul style="list-style-type: none"> • Generate a stop condition. • Set the STOP bit in the ICSR register to 1.

5. Description of Software

5.1 Modules

Table 6 describes the modules used in the sample application.

Table 6 Description of Modules

Module Name	Label Name	Description
Main function	main()	Sets the EEPROM read start address, and calls the data read function.
I ² C2 initialization function	init_iic()	Cancels module standby mode, and configures the PFC and I ² C2.
Data read function	read_EEPROM()	Generates a start condition, reads data from the EEPROM, and generates a stop condition.
EEPROM address transmission function	set_addr_EEPROM()	Generates a start condition and a slave address, and sets the EEPROM address.
EEPROM bus initialization function	init_EEPROM()	Forcibly initializes the SDA bus that has hanged up due to a communication error or other reason.
I ² C2 reset function	reset_iic()	Resets and halts the I ² C2 module.
Start condition generation function	iic_start()	Generates a start condition through port processing.
Output level set function	iic_sda_out()	Sets the output level of the bus line.
Transmit data set function	iic_set()	Outputs the clock and transmit data through port processing.
1-byte transmission function	iic_bytesend()	Transmits 1 byte of data through port processing.
Acknowledge reception function	iic_ackck()	Receives the acknowledge from the EEPROM through port processing.
Stop condition generation function	iic_stop()	Generates a stop condition through port processing.
Software wait function	wait_timer()	Wait timer using a software counter

5.2 Variables

Table 7 lists the variables used in the sample application.

Table 7 Description of Variables

Label Name of Variable	Function	Used In
read_data[0:9]	Array for storing read data	Main function
address	Read start address of the EEPROM	Main function
addr	Copy of read start address of the EEPROM	Data read function EEPROM address transmission function
*r_data	Pointer variable to the array for storing read data	Data read function
num	Number of received data bytes	Data read function
ack	Acknowledge determination flag	Data read function
count	Counter for continuous data reading	Data read function
dummy	Variable for dummy reading	Data read function
data	Information of output levels on the PB2 (SCL) and PB3 (SDA) pins	Output level set function
scl	Information of output levels on the SCL line	Transmit data set function
sda	Information of output levels on the SDA line	Transmit data set function
tx_data	One byte of data for transmission through port processing	1-byte transmission function
ck_bit	Clock information for data transmission through port processing	1-byte transmission function
bit_data	One bit of data for transmission through port processing	1-byte transmission function
ack_flag	Acknowledge bit received through port processing	Acknowledge reception function
wait_cnt	Count value for software timer	Software wait function
cnt	Variable for software counter	Software wait function

5.3 Register Settings

The register settings used in the sample application are described below. Note that the set values are specifically used in the sample task and that they are different from the initial values.

5.3.1 Settings for the Clock Pulse Generator (CPG)

- Frequency Control Register (FRQCR)
 - Set value: H'0241
 - Function: Specifies the frequency division ratio.

Bit	Bit Name	Value	Description
15	—	0	Reserved
14 to 12	IFC[2] to IFC[0]	000	Frequency division ratio for internal clock (I ϕ) 000: $\times 1$ (80 MHz when input clock is 10 MHz)
11 to 9	BFC[2] to BFC[0]	001	Frequency division ratio for bus clock (B ϕ) 001: $\times 1/2$ (40 MHz when input clock is 10 MHz)
8 to 6	PFC[2] to PFC[0]	001	Frequency division ratio for peripheral clock (P ϕ) 001: $\times 1/2$ (40 MHz when input clock is 10 MHz)
5 to 3	MIFC[2] to MIFC[0]	000	Frequency division ratio for MTU2S clock (MI ϕ) 000: $\times 1$ (80 MHz when input clock is 10 MHz)
2 to 0	MPFC[2] to MPFC[0]	001	Frequency division ratio for MTU2 clock (MP ϕ) 001: $\times 1/2$ (40 MHz when input clock is 10 MHz)

5.3.2 Settings for Power-Down Modes

- Standby Control Register 3 (STBCR3)
 - Set value: H'7F
 - Function: Controls the operation of individual modules in power-down modes.

Bit	Bit Name	Value	Description
7	MSTP15	0	0: The I ² C2 runs.
6	MSTP14	1	1: Stops supply of the clock signal to the SCIF.
5	MSTP13	1	1: Stops supply of the clock signal to SCI_2.
4	MSTP12	1	1: Stops supply of the clock signal to SCI_1.
3	MSTP11	1	1: Stops supply of the clock signal to SCI_0.
2	MSTP10	1	1: Stops supply of the clock signal to the SSU.
1 and 0	—	11	Reserved

5.3.3 Settings for I²C Bus Interface 2 (I²C2)

- I²C Bus Control Register 1 (ICCR1)

- Set value: H'B5

- Function: Selects the operating mode and transfer clock of the I²C2.

Bit	Bit Name	Value	Description
7	ICE	1	1: Enables transfer operation (the SCL/SDA buses are driven).
6	RCVD	0	0: Performs the next reception when ICDRR is read.
5	MST	1	MST: Master/Slave Select
4	TRS	1*	TRS: Transmit/Receive Select 10: Master reception mode 11: Master transmission mode.
3 to 0	CKS[3] to CKS[0]	0101	Transfer Clock Select 0101: Sets the transfer rate to 400 kHz (P _φ = 40 MHz).

Note: * Changed to 0 (reception) after an address is transmitted to the EEPROM.

- I²C Bus Control Register 2 (ICCR2)

- Setting value: H'7D

- Function: Generates start and stop conditions, drives the SDA pin, monitors the SCL pin, and controls resetting of the I²C bus control circuitry.

Bit	Bit Name	Value	Description
7	BBSY	0*	Indicates whether the I ² C bus is occupied or released, and generates start and stop conditions. 0: I ² C bus is released.
6	SCP	1*	Controls generation of start and stop conditions.
5	SDAO	1	1: The output on the SDA pin is high (when read). Changes the output on the SDA pin to Hi-Z (when written).
4	SDAOP	1	SDAO Write Protect Write 0 to this bit when writing to SDAO.
3	SCLO	1	1: The output on the SCL pin is high (read-only bit).
2	—	1	Reserved
1	IICRST	0	I ² C Control Unit Reset Resets the control circuitry of the I ² C when 1 is written.
0	—	1	Reserved

Note: * To generate a start condition, write b'10 to BBSY and SCP.

To generate a stop condition, write b'00 to BBSY and SCP.

- I²C Bus Mode Register (ICMR)
 - Setting value: H'38
 - Function: Selects MSB- or LSB-first transfer, controls the wait states in master mode, and selects the number of bits to be transferred.

Bit	Bit Name	Value	Description
7	MLS	0* ¹	0: MSB-first
6	WAIT	0* ²	0: Data and acknowledge bit are transferred continuously.
5 and 4	—	11	Reserved
3	BCWP	1	BC Write Protect Write 0 to this bit when writing to the BC[2] to BC[0] bits.
2 to 0	BC[2] to BC[0]	000	000: 9 bits (data and acknowledge bit) are transferred.

- Notes: 1. This bit must be set to 0 (MSB-first) when the I²C bus format is used.
 2. This bit must be set to 0.

- I²C Bus Interrupt Enable Register (ICIER)
 - Setting value: H'04
 - Function: Enables or disables interrupt sources and controls the acknowledge bit.

Bit	Bit Name	Value	Description
7	TIE	0	0: Disables the transmit data empty interrupt request (IITXI).
6	TEIE	0	0: Disables the transmit end interrupt request (IITEI).
5	RIE	0	0: Disables the receive data full interrupt request (IIRXI).
4	NAKIE	0	0: Disables the NACK receive interrupt request (IINAKI).
3	STIE	0	0: Disables the stop condition detection interrupt request (IISTPI).
2	ACKE	1	1: Halts data transfer when the received acknowledge bit is 1.
1	ACKBR	0	Holds the acknowledge data in transmission mode (read-only bit).
0	ACKBT	0	0: Transmits ACK = 0 in reception mode.

- I²C Bus Status Register (ICSR)
 - Setting value: H'00
 - Function: Provides various interrupt request and status flags.

Bit	Bit Name	Value	Description
7	TDRE	0	Transmit data register empty flag
6	TEND	0	Transmit end flag
5	RDRF	0	Receive data register full flag
4	NACKF	0	No acknowledge detection flag
3	STOP	0	Stop condition detection flag
2	AL/OVE	0	Arbitration lost flag/overrun error flag
1	AAS	0	Slave address recognition flag
0	ADZ	0	General call address recognition flag

- I²C Bus Transmit Data Register (ICDRT)
 - Setting value: H'FF (initial value)
 - Function: Holds data for transmission.
- I²C Bus Receive Data Register (ICDRR)
 - Setting value: H'FF
 - Function: Holds the received data. (Read only)

5.3.4 Settings for the Pin Function Controller (PFC)

- Port B Control Register L1 (PBCRL1)
 - Setting value: H'4400
 - Function: Selects the functions of the multiplexed pins on port B (PB3 to PB0).

Bit	Bit Name	Value	Description
15	—	0	Reserved
14 to 12	PB3MD[2] to PB3MD[0]	100*	PB3 mode 100: SDA I/O (I ² C2)
11	—	0	Reserved
10 to 8	PB2MD[2] to PB2MD[0]	100*	PB2 mode 100: SCL I/O (I ² C2)
7	—	0	Reserved
6 to 4	PB1MD[2] to PB1MD[0]	000	PB1 mode 000: PB1 I/O (port)
3	—	0	Reserved
2 to 0	PB0MD[2] to PB0MD[0]	000	PB0 mode 000: PB1 I/O (port)

Note: * In EEPROM bus initialization, these bits are set to 000 to use the multiplexed pins as general I/O (port) pins.

- Port B IO Register (PBIORL)
 - Set value: H'000C
 - Function: Selects the signal directions on the port B pins.

Bit	Bit Name	Value	Description
15 to 10	—	All 0	Reserved
9	PB9IOR	0	0: PB9 is input.
8	PB8IOR	0	0: PB8 is input.
7	PB7IOR	0	0: PB7 is input.
6	PB6IOR	0	0: PB6 is input.
5	PB5IOR	0	0: PB5 is input.
4	PB4IOR	0	0: PB4 is input.
3	PB3IOR	1	1: PB3 is output (ignored when SDA is selected by PBCRL1).
2	PB2IOR	1	1: PB2 is output (ignored when SCL is selected by PBCRL1).
1	PB1IOR	0	0: PB1 is input.
0	PB0IOR	0	0: PB0 is input.

Note: This setting is used in EEPROM bus initialization.

5.3.5 Settings for I/O Ports

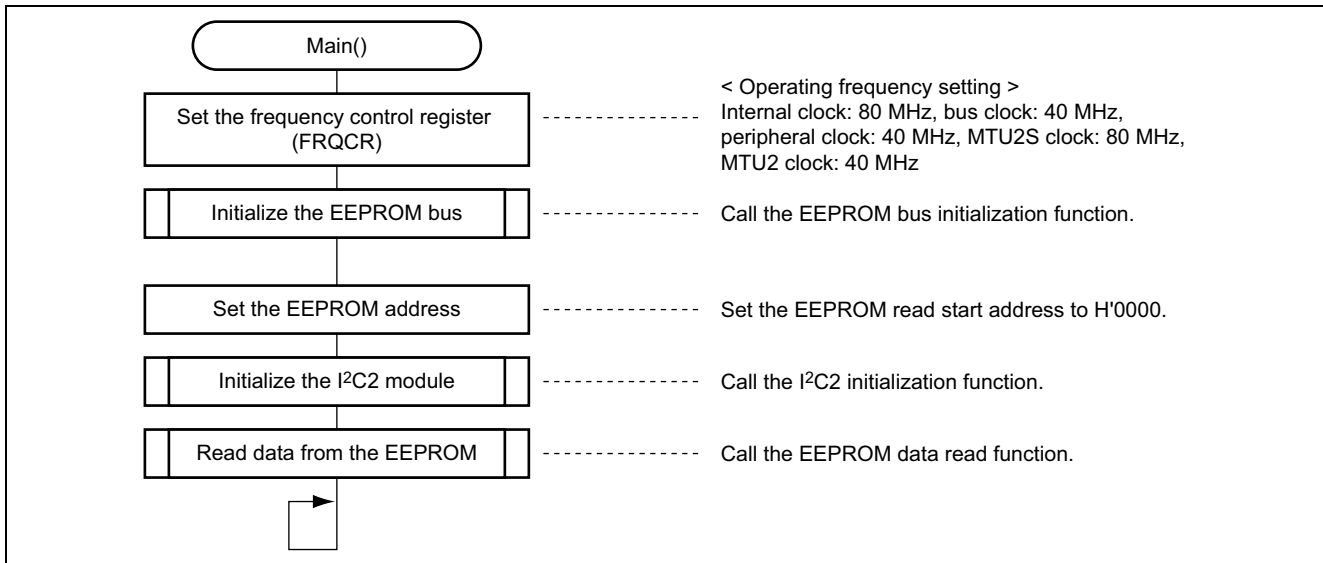
- Port B Data Register L (PBDRL)
 - Set value: H'000C
 - Function: Holds the data for port B.

Bit	Bit Name	Value	Description
15 to 10	—	All 0	Reserved
9	PB9DR	0	0: Low level on PB9
8	PB8DR	0	0: Low level on PB8
7	PB7DR	0	0: Low level on PB7
6	PB6DR	0	0: Low level on PB6
5	PB5DR	0	0: Low level on PB5
4	PB4DR	0	0: Low level on PB4
3	PB3DR	1	1: High level on PB3 (Produces a transmit data signal in EEPROM bus initialization.)
2	PB2DR	1	1: High level on PB2 (Produces a clock signal in EEPROM bus initialization.)
1	PB1DR	0	0: Low level on PB1
0	PB0DR	0	0: Low level on PB0

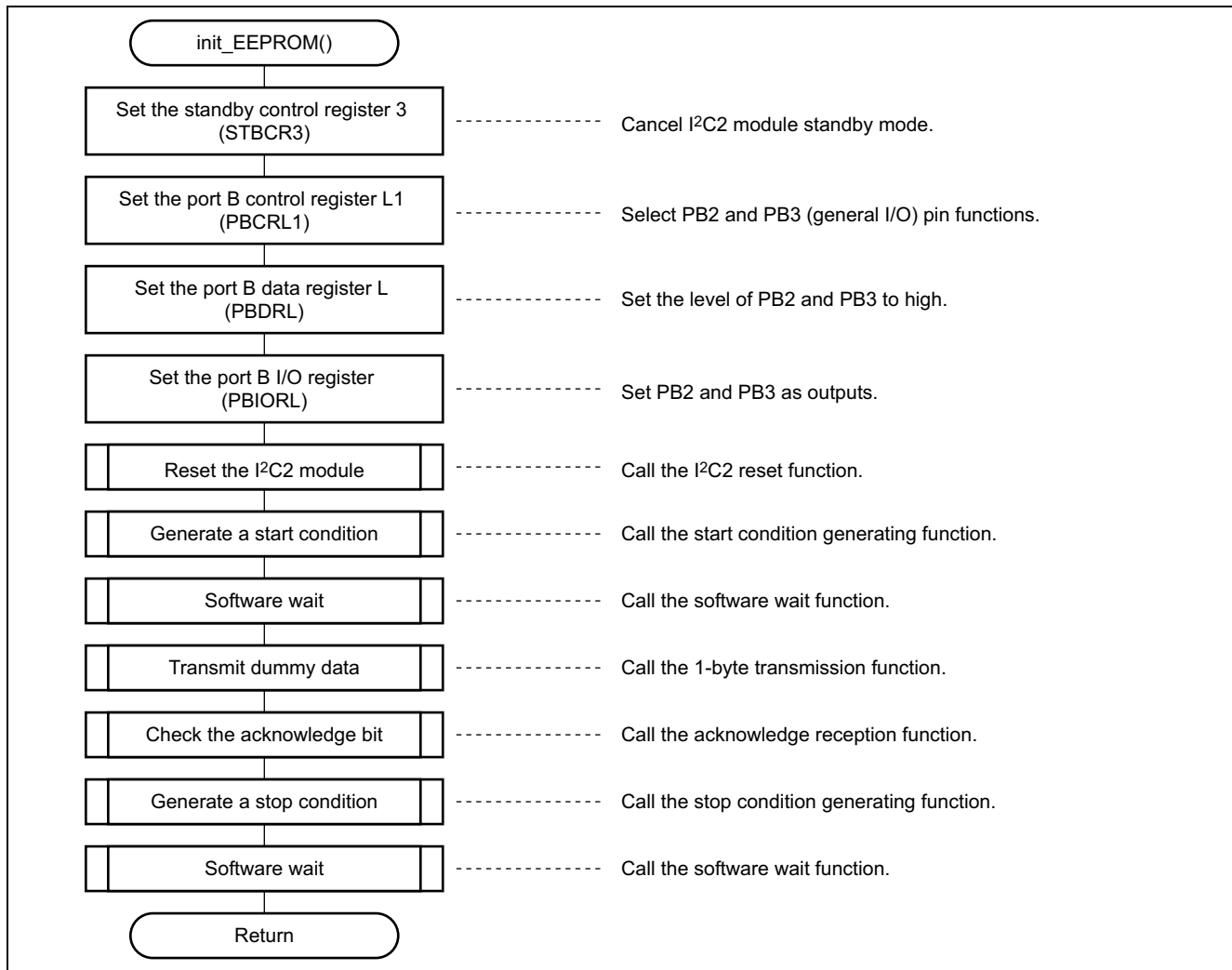
Note: This setting is used in EEPROM bus initialization.

6. Flowcharts

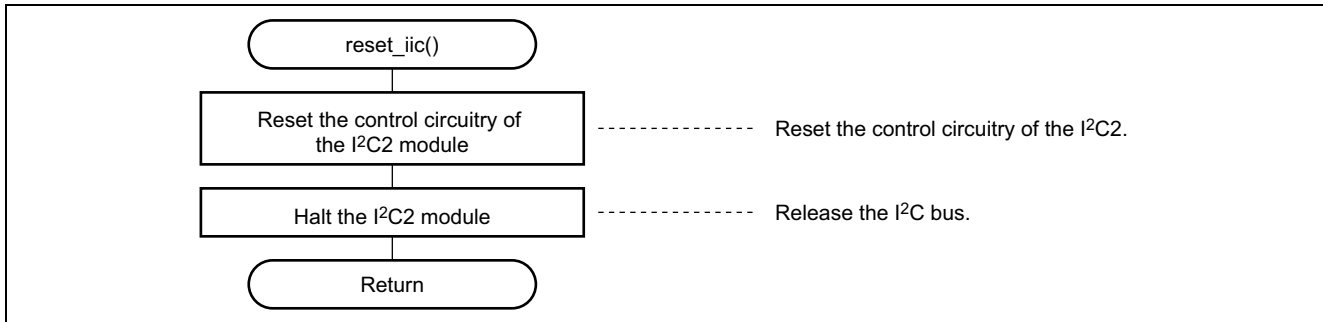
6.1 Main Function



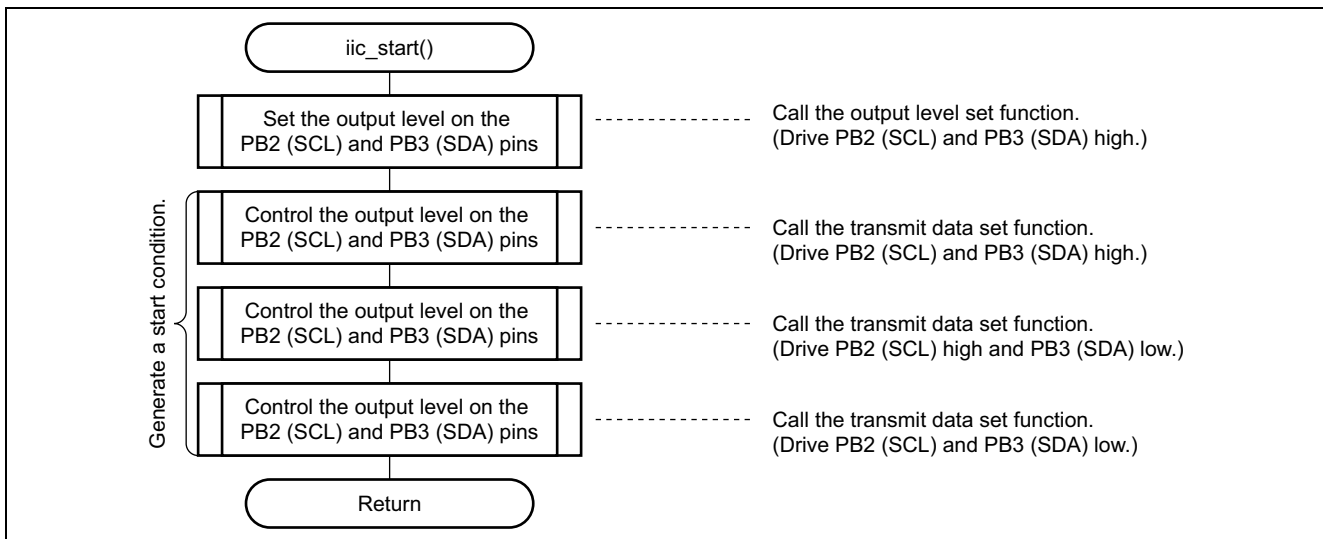
6.2 EEPROM Bus State Initialization Function



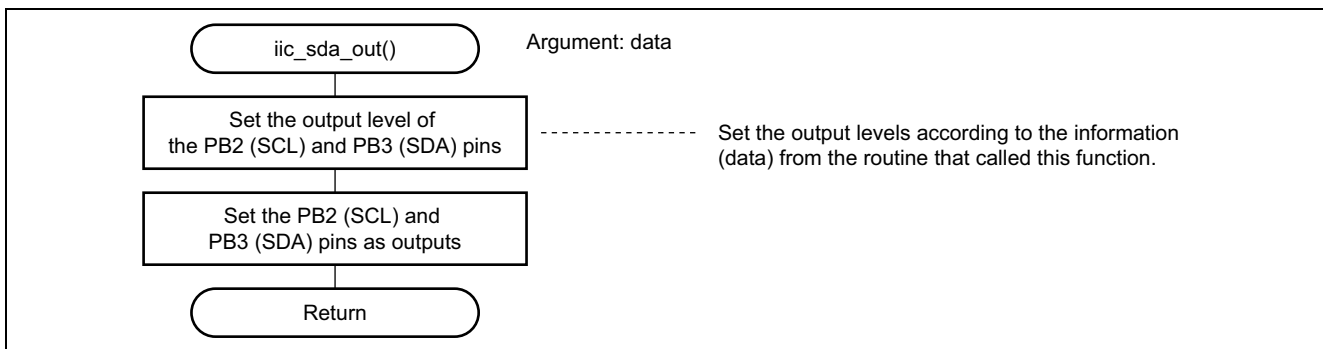
6.2.1 I²C Reset Function



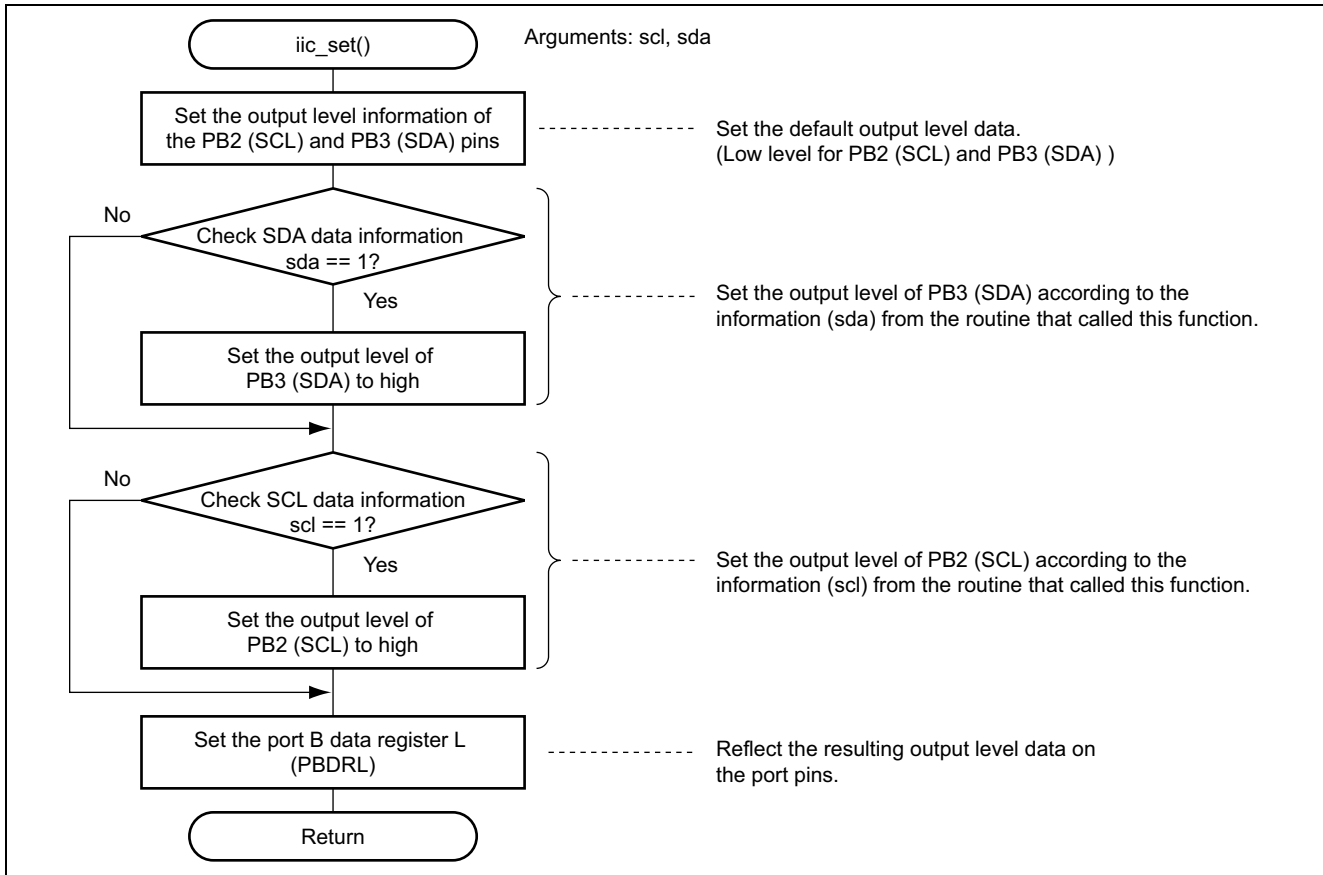
6.2.2 Start Condition Generation Function



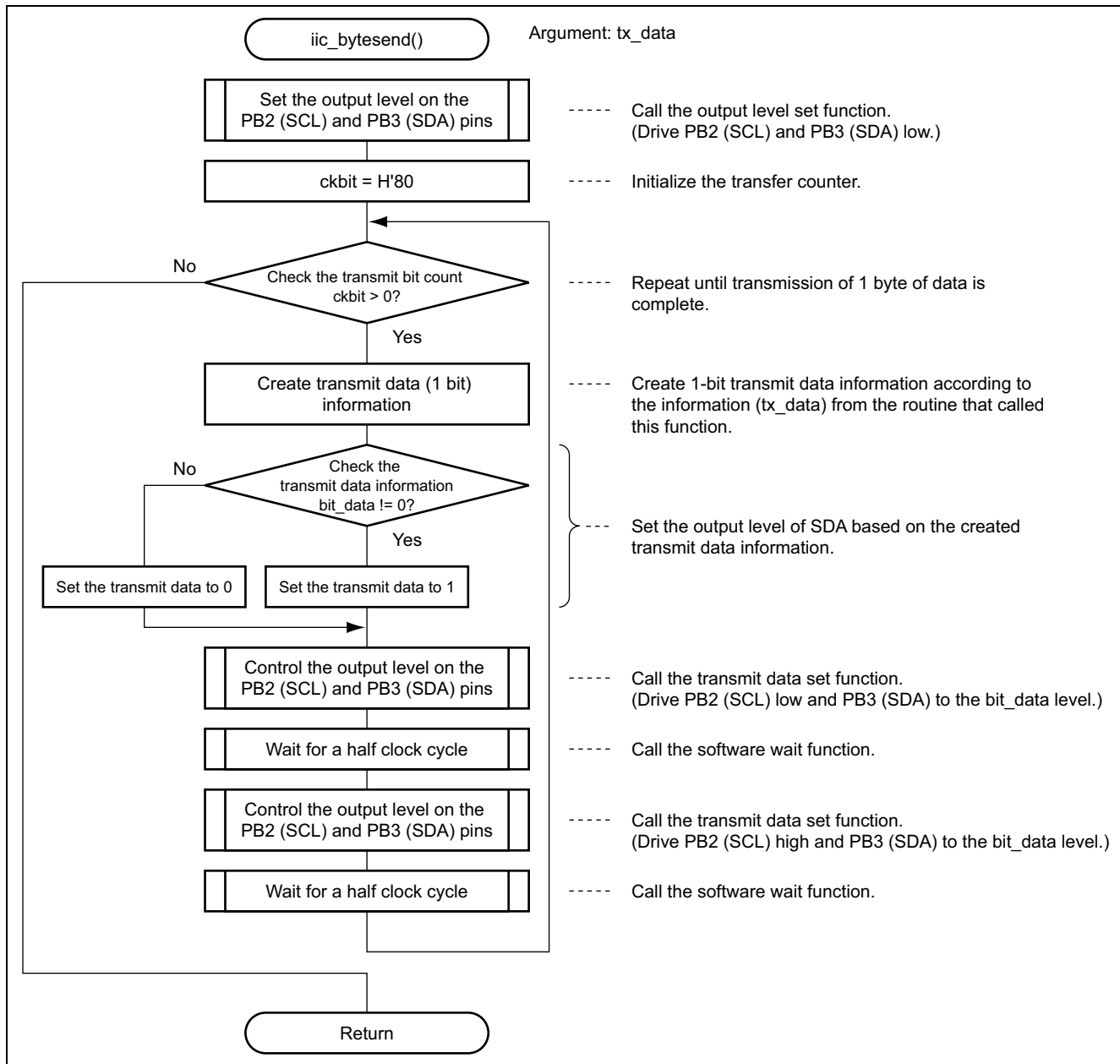
6.2.3 Output Level Set Function



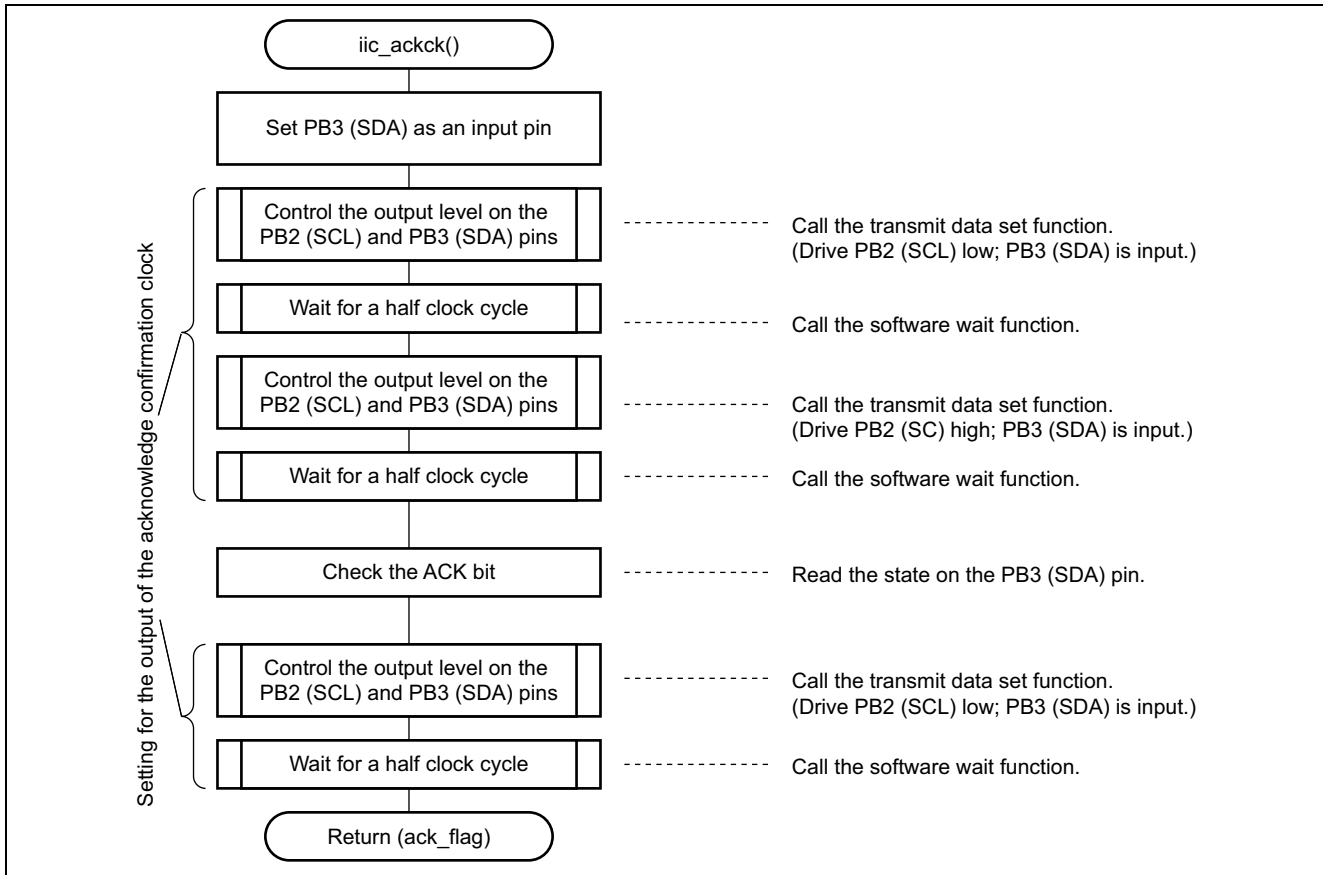
6.2.4 Transmit Data Set Function



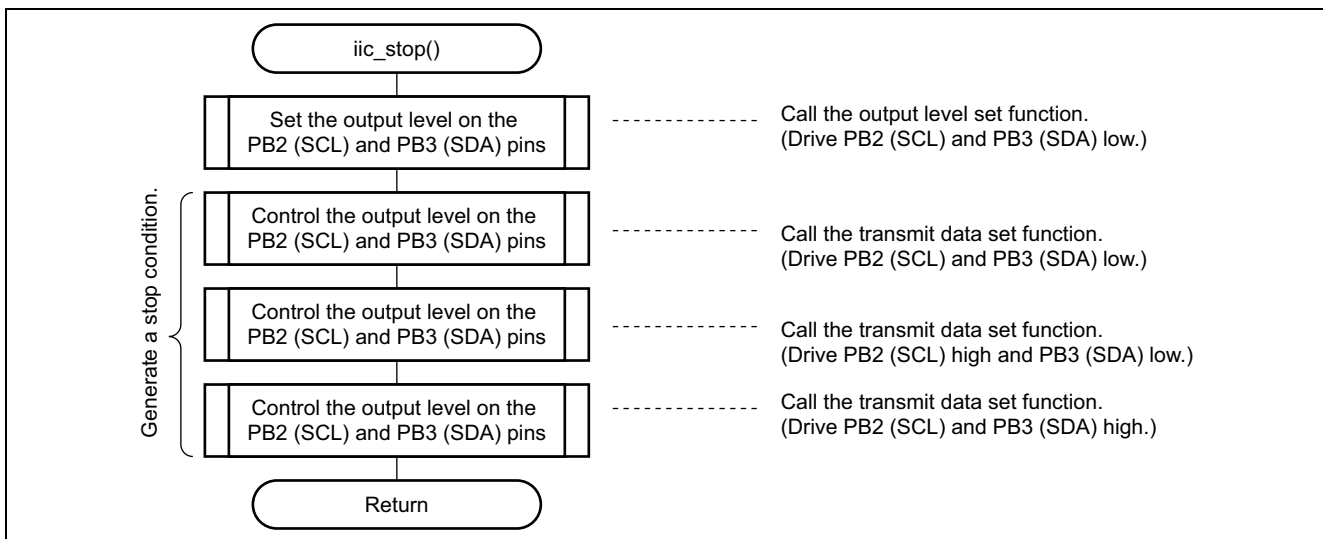
6.2.5 1-Byte Transmission Function



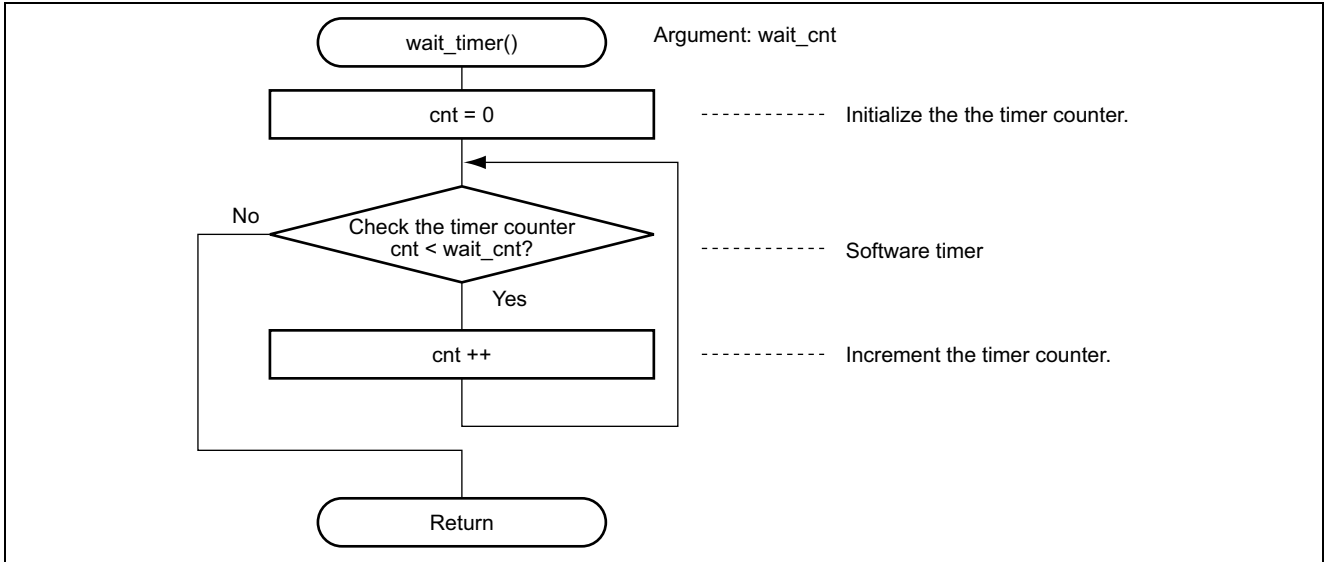
6.2.6 Acknowledge Reception Function



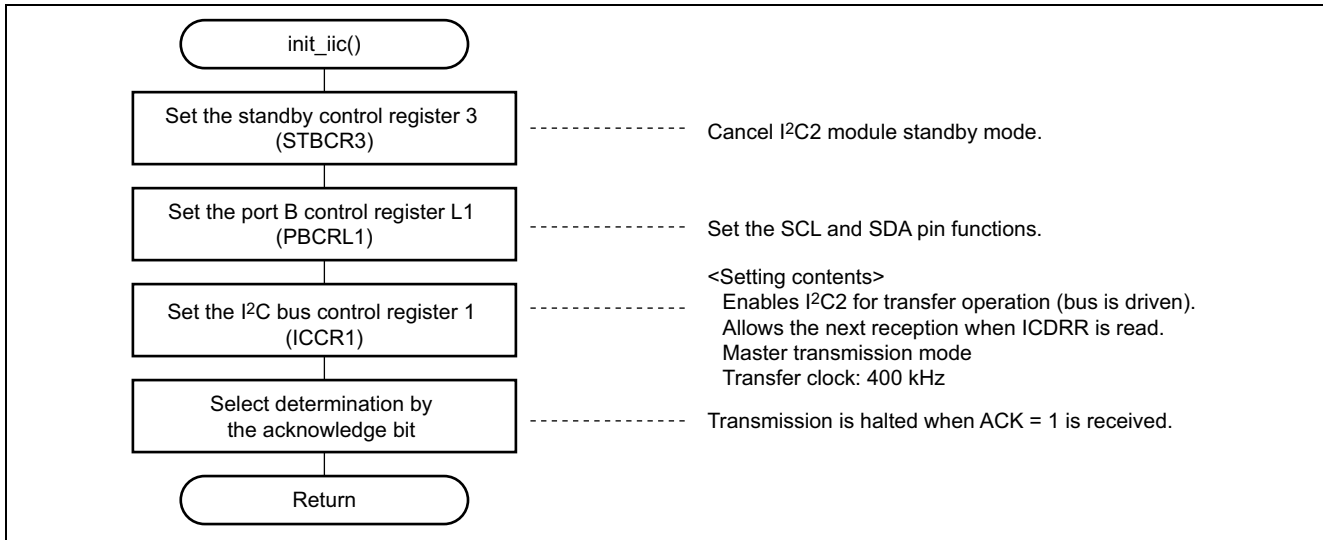
6.2.7 Stop Condition Generation Function



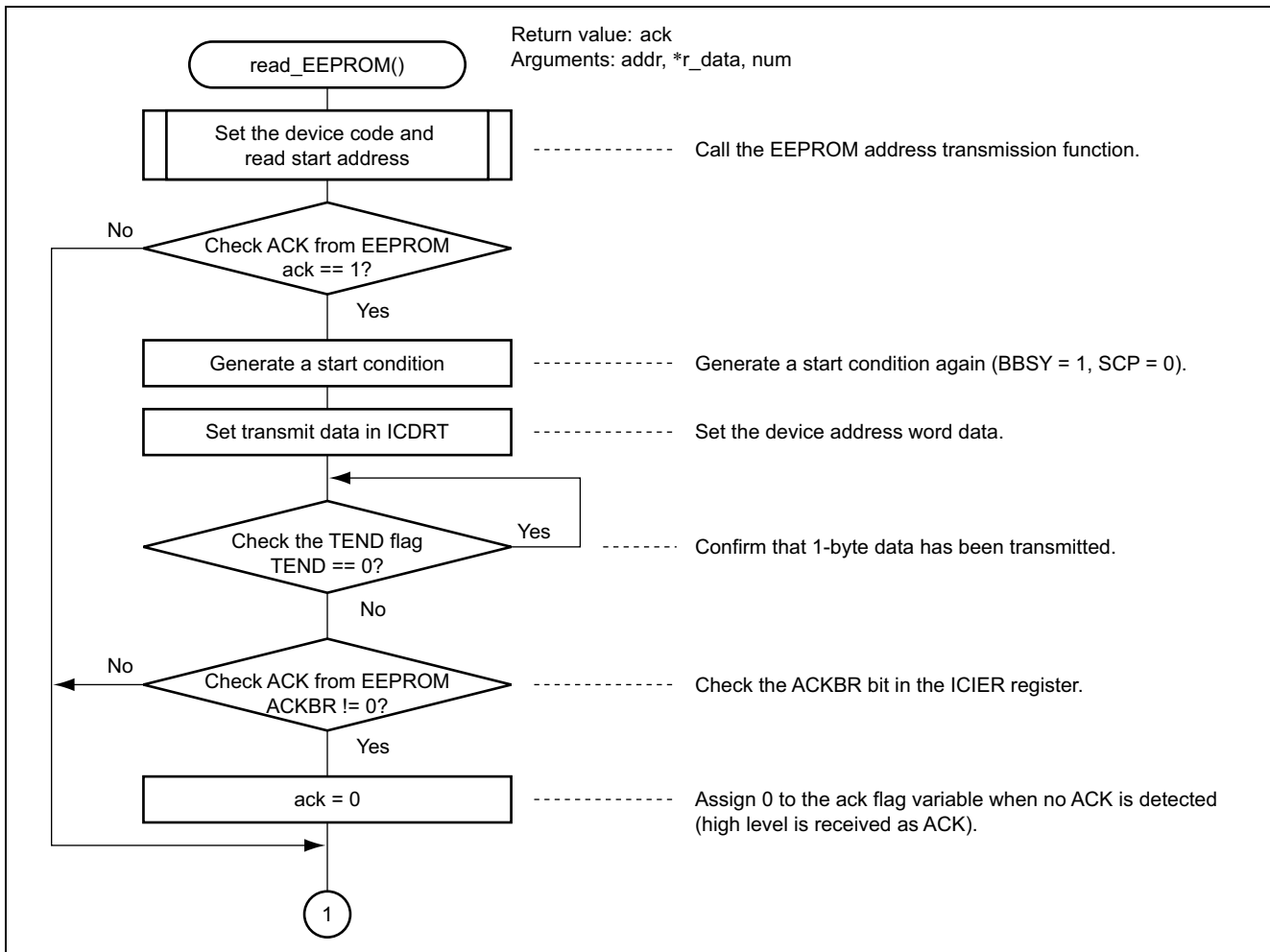
6.2.8 Software Wait Function

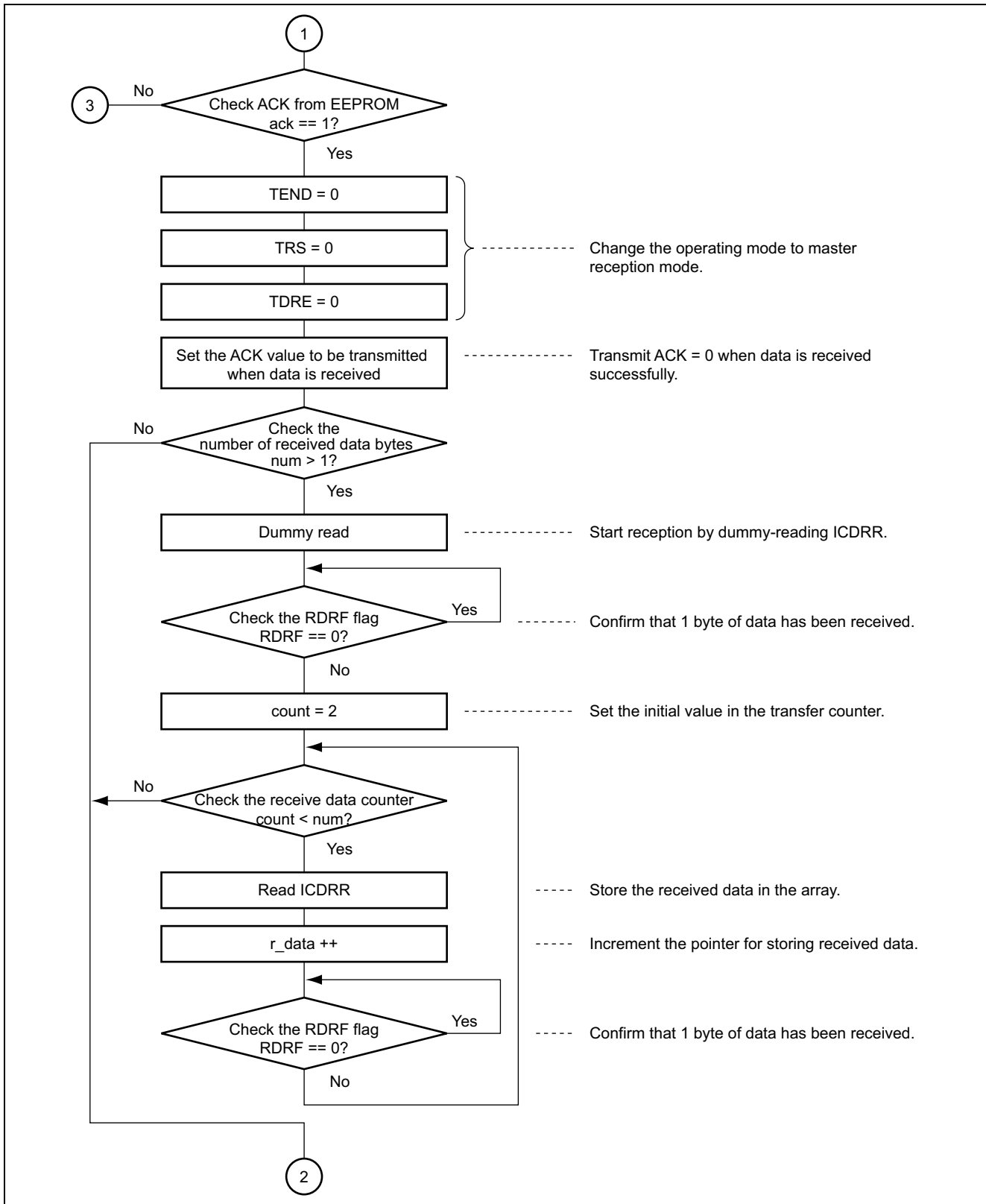


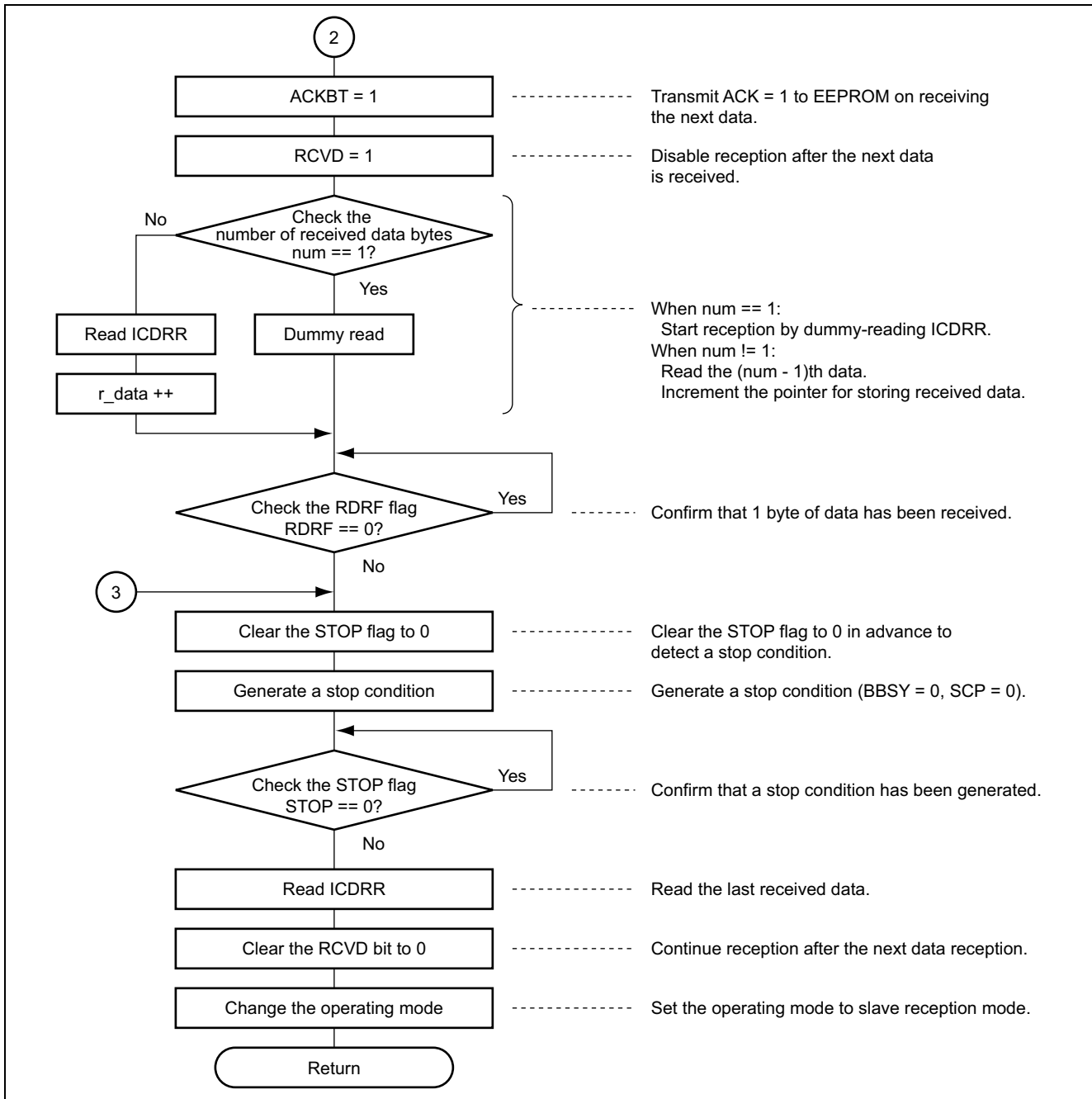
6.3 I²C Initialization Function



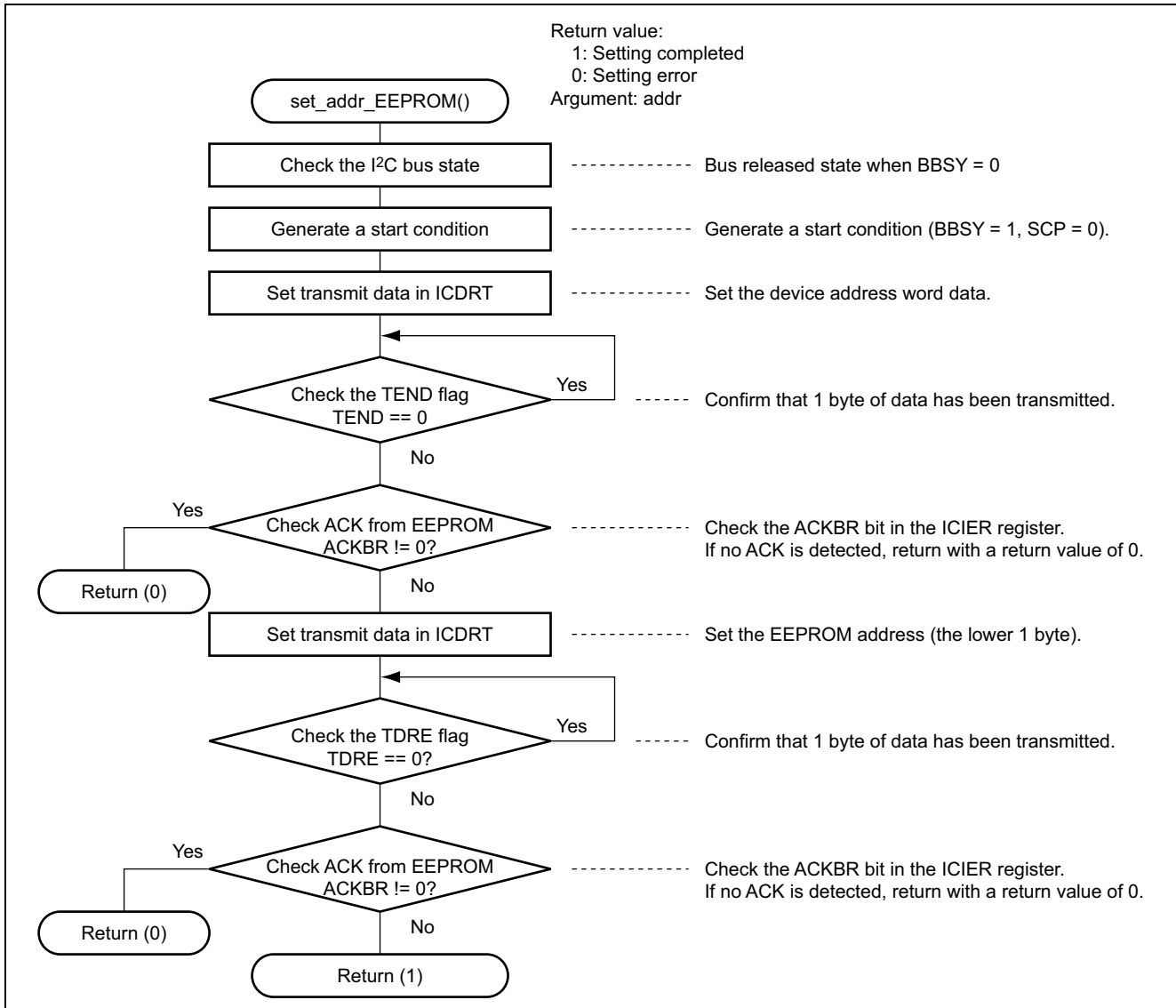
6.4 Data Read Function







6.4.1 EEPROM Address Transmission Function



7. Website

- Website of Renesas Technology Corp.
<http://www.renesas.com/>

Revision Record

Rev.	Date	Description	
		Page	Summary
1.00	Sep.14.05	—	First edition issued

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